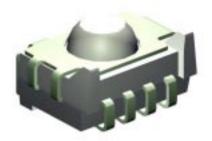


## IR Receiver for High Data Rate PCM at 455kHz

### **Description**

The TSOP5700 is a miniaturized SMD IR receiver for infrared remote control and IR data transmission. PIN diode and preamplifier are assembled on lead frame, the epoxy package is designed as IR filter. The demodulated output signal can directly be decoded by a microprocessor. The main benefit is the operation with high data rates and long distances.



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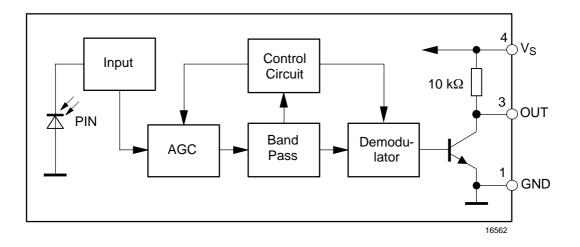
#### **Features**

- Photo detector and preamplifier in one package
- Internal Bandfilter for PCM frequency
- Internal shielding against electrical field disturbance
- TTL and CMOS compatibility
- Output active low

#### **Special Features**

- Data rate 20 kbit/s
- Small size package
- Supply voltage 2.7 − 5.5V
- Short settling time after power on
- High envelope duty cycle can be received
- Enhanced immunity against disturbance from energy saving lamps
- Taping available for topview and sideview assembly

## **Block Diagramm**



# **TSOP5700**

# Vishay Semiconductors



## **Absolute Maximum Ratings**

 $T_{amb} = 25^{\circ}C$ 

Parameter	Test Conditions	Symbol	Value	Unit
Supply Voltage	Pin 4	V <sub>S</sub>	-0.36.0	V
Voltage at output to supply	Pin 3	$V_S - V_O$	-0.3V <sub>S</sub> +0.3	V
Supply Current	Pin 4	I <sub>S</sub>	5	mA
Output Voltage	Pin 3	Vo	-0.36.0	V
Output Current	Pin 3	Io	15	mA
Junction Temperature		T <sub>i</sub>	100	°C
Storage Temperature Range		T <sub>stg</sub>	-40+85	°C
Operating Temperature Range		T <sub>amb</sub>	-25+85	°C
Power Consumption	T <sub>amb</sub> ≦ 85°C	P <sub>tot</sub>	50	mW

## **Basic Characteristics**

 $T_{amb} = 25^{\circ}C$ 

Parameter	Test Conditions	Symbol	Min.	Тур.	Max.	Unit
Supply Current (Pin 4)	Dark ambient	I <sub>SD</sub>		2.0	2.7	mA
	$E_V = 40 \text{ klx, sunlight}$	I <sub>SH</sub>		2.3		mA
Supply Voltage (Pin 4)		Vs	2.7	5	5.5	V
Transmission Distance	$\lambda_{p} {=}~870$ nm, IR Diode TSHF5400, $I_{F} {=}~300$ mA	d <sub>max</sub>		15		m
	$\lambda_{p} =$ 950 nm, IR Diode TSAL6400, $I_{F} =$ 300 mA	d <sub>max</sub>		9		m
Threshold Irradiance	$\lambda_p$ = 870 nm, optical test signal of Fig.1	E <sub>e min</sub>		1.5	2.5	mW/m <sup>2</sup>
Maximum Irradiance	Optical test signal of Fig.1	E <sub>e max</sub>	30			W/m <sup>2</sup>
Output Voltage Low (Pin 3)	1kΩ external pull up resistor	$V_{QL}$			100	mV
Output Voltage High (Pin 3)	No external pull-up resistor	$V_{QH}$	$V_{S} - 0.25$			V
Bandpassfilter quality		Q		10		
Out–Pulse width tolerance	Optical test signal of Fig.1, 2.5 mW/m <sup>2</sup> $\leq$ E <sub>e</sub> $\leq$ 30 W/m <sup>2</sup>	$\Delta_{tpo}$	<b>–15</b>	+5	+15	μs
Delay time of output pulse	Optical test signal of Fig.1, E <sub>e</sub> > 2.5 mW/m <sup>2</sup>	t <sub>don</sub>	15		36	μs
Receiver start up time	Valid data after power on	t <sub>V</sub>		50		μs
Falling time	Leading edge of output pulse	t <sub>f</sub>		0.4		μs
Rise time	No external pull up resistor	t <sub>r</sub>		12		μs
	1kΩ external pull up resistor	t <sub>r</sub>		1.2		μs
Directivity	Angle of half transmission distance	φ <sub>1/2</sub>		±50		deg



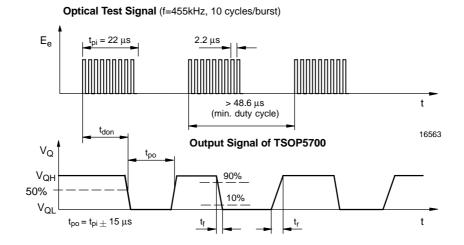
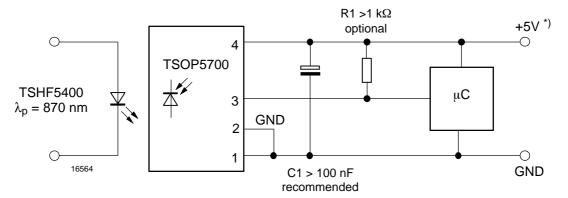


Figure 1. Output Function

## **Application Circuit**



\*) tolerated supply voltage range: 2.7 V < V $_{\rm S}$  < 5.5 V, with the resistor R1 the slopes of the output pulse are becoming faster.

#### **Recommendation for Suitable Data Formats**

The circuit of the TSOP5700 is designed in that way that disturbance signals are identified and unwated output pulses due to noise or disturbances are avoided. A bandpassfilter, an automatic gain control and an integrator stage is used to suppress such disturbances. The distinguishing marks between data signal and disturbance are carrier frequency, burst length and the envelope duty cycle.

The data signal should fullfill the following conditions:

- The carrier frequency should be close to 455 kHz.
- The burstlength should be at least 22 μs (10 cycles of the carrier signal) and shorter than 500 μs.
- $\bullet~$  The separation time between two consecutive bursts should be at least 26  $\mu s.$
- If the data bursts are longer than 500 μs then the envelope duty cycle is limited to 25%.
- The duty cycle of the carrier signal (455 kHz) may be between 50% (1.1 μs pulses) and 10% (0.2 μs pulses).
  The lower duty cycle may help to save battery power.

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## **Typical Characteristics** (T<sub>amb</sub> = 25°C, unless otherwise specified)

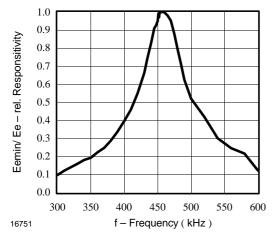


Figure 2. Frequency Dependence of Responsivity

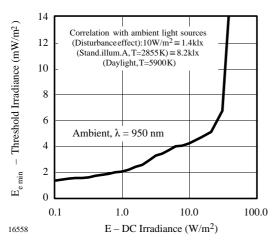


Figure 3. Sensitivity in Bright Ambient

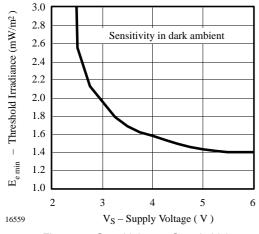


Figure 4. Sensitivity vs. Supply Voltage

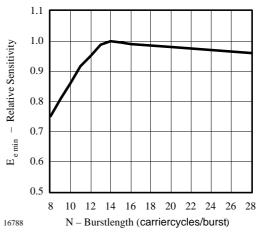


Figure 5. Rel. Sensitivity vs. Burstlength

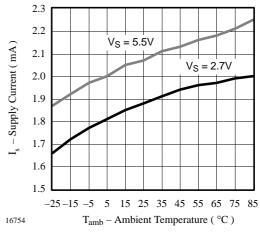


Figure 6. Supply Current vs. Ambient Temperature

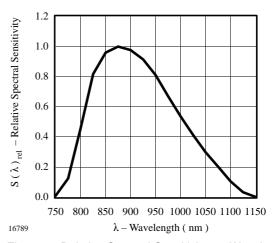


Figure 7. Relative Spectral Sensitivity vs. Wavelength





(IR diode TSHF5400,  $\lambda_p$  870 nm, I<sub>F</sub> = 300 mA, f = 455 kHz, 10 cycles/burst)

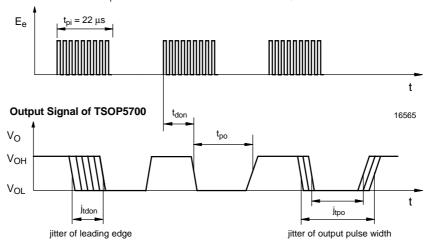


Figure 8. Output Function

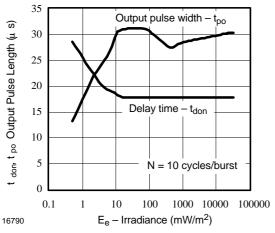


Figure 9. Output Pulse Diagram

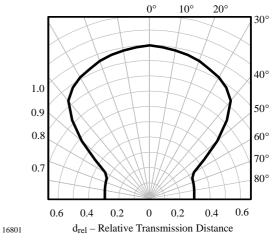


Figure 11. Directivity

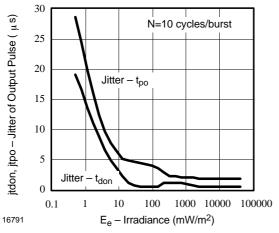


Figure 10. Jitter of Output Pulse vs. Irradiance



#### **Operating Instructions**

#### **Reflow Soldering**

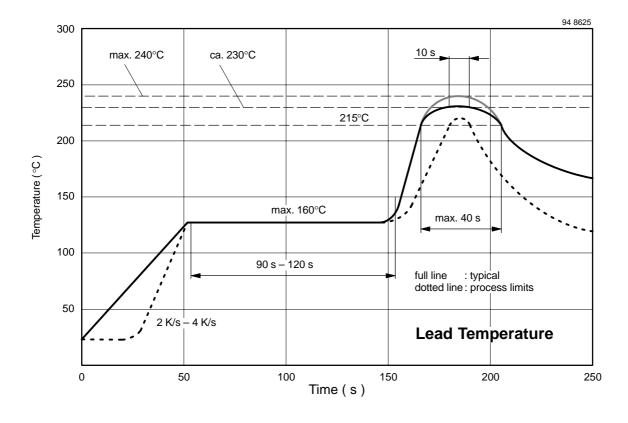
- Reflow soldering must be done within 48 hours stored under max. 30°C, 80% RH after opening envelop
- Recommended soldering paste (composition: SN 63%, Pb 37%)
   Melting temperature 178°C to 192°C
- Apply solder paste to the specified soldering pads, by using a dispenser or by screen printing.
- Recommended thickness of metal mask is 0.2 mm for screen printing.
- The recommended reflow furnace is a combinationtype with upper and lower heaters.
- Set the furnace temperatures for pre-heating and heating in accordance with the reflow temperature profile as shown below. Excercise extreme care to keep the maximum temperature below 230°C. The following temperature profile means the tempera– ture at the device surface. Since temperature differ– ence occurs between the work and the surface of the circuit board depending on the pes of circuit board or reflow furnace, the operating conditions should be verified prior to start of operation.
- Handling after reflow should be done only after the work surface has been cooled off.

#### **Manual Soldering**

- Use the 6/4 solder or the solder containing silver.
- Use a soldering iron of 25 W or smaller. Adjust the temperature of the soldering iron below 300°C.
- Finish soldering within three seconds.
- Handle products only after the temperature is cooled off.

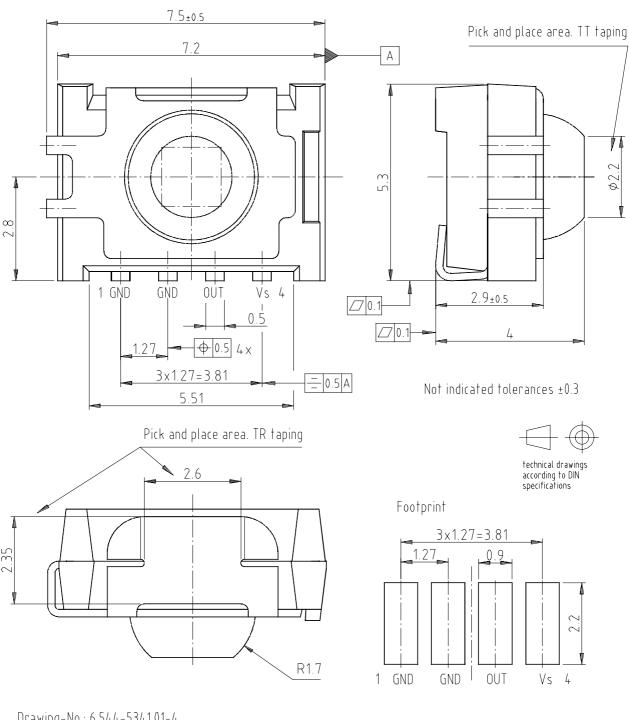
#### Cleaning

- Perform cleaning after soldering strictly in conformance to the following conditions:
   Cleaning agent:
   2-propanol (isopropyl alcohol).
   Commercially available grades (industrial use) should be used.
   Demineralized or distilled water having a resistivity of not less than 500 mΩ corresponding to a conductivity of 2 mS/m.
- Temperature and time: 30 seconds under the temperature below 50°C or 3 minutes below 30°C.
- Ultrasonic cleaning: Below 20 W.





### **Dimensions in mm**



Drawing-No.: 6.544-5341.01-4

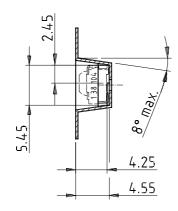
Issue: 4; 08.11.01

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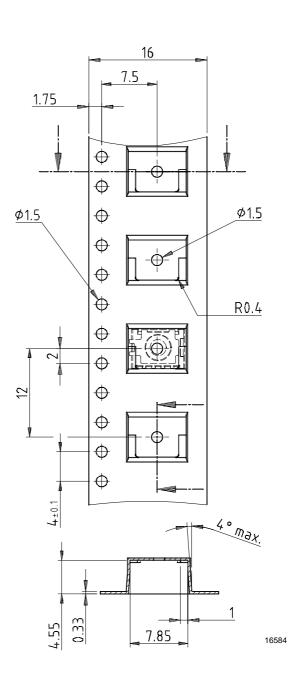
## **Taping Version TSOP5700TT**





Drawing-No.: 9.700-5259.01-4

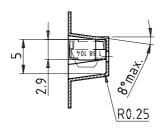
Issue: 1; 05.09.01

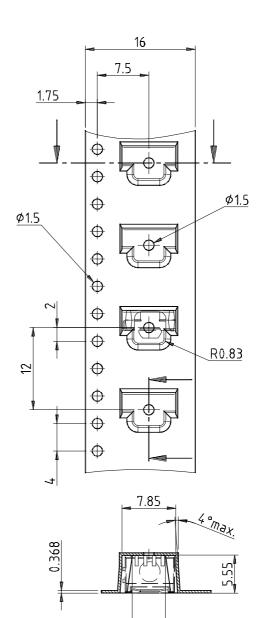




## **Taping Version TSOP5700TR**







4.85

Drawing-No.: 9.700-5260.01-4

Issue: 2; 25.09..01

16585



#### **Ozone Depleting Substances Policy Statement**

It is the policy of Vishay Semiconductor GmbH to

- 1. Meet all present and future national and international statutory requirements.
- 2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

**Vishay Semiconductor GmbH** has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

- 1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
- Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
- 3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design and may do so without further notice. Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use Vishay Telefunken products for any unintended or unauthorized application, the buyer shall indemnify Vishay Telefunken against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

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